

Title (en)

MOLDABLE COMPOSITE ARTICLE AND METHOD OF MANUFACTURE

Title (de)

FORMBARER GEGENSTAND UND VERFAHREN ZUR HERSTELLUNG

Title (fr)

ARTICLE COMPOSITE MOULABLE ET SON PROCEDE DE FABRICATION

Publication

EP 1171291 A4 20020911 (EN)

Application

EP 00913664 A 20000229

Priority

- US 0005151 W 20000229
- US 28691699 A 19990406

Abstract (en)

[origin: WO0059716A1] An article (1) which includes a layer of formable fabric (5) of the type which when subjected to molding under heat and/or pressure possesses a high degree of stiffness. A layer of variable compression fabric (2) capable of assuming variable thickness when subjected to molding under heat and/or pressure is bonded to the surface of the formable fabric (5), where the layers are made of the same thermoformable polymeric chemical substance.

IPC 1-7

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IPC 8 full level

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CPC (source: EP KR)

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B32B 2307/738 (2013.01 - KR); **B32B 2605/003** (2013.01 - KR)

Citation (search report)

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- [X] EP 0591801 A1 19940413 - UNITIKA LTD [JP]
- [PX] WO 9921697 A1 19990506 - DOW CHEMICAL CO [US], et al
- [A] WO 9830375 A1 19980716 - OWENS CORNING FIBERGLASS CORP [US]
- [A] PATENT ABSTRACTS OF JAPAN vol. 010, no. 044 (M - 455) 21 February 1986 (1986-02-21)
- [A] PATENT ABSTRACTS OF JAPAN vol. 018, no. 559 (M - 1692) 25 October 1994 (1994-10-25)
- See also references of WO 0059716A1

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